

Approval Sheet

Products	CHIP Antenna	Antenna
Supplier CODE	ACS2450FBAS30	49304R0
Model	GBH-S300	TODGSON
SEC CODE		ТОР
Revision	VER.1.0 12/16	
Supplier	Partron	воттом

MSL	LEAD FREE	BFRs-Free, Halogen-Free
MSL 1	LEAD-FREE	BFRs/CFRs/PVC-Free

Drafter	Research 5Team	Quality Assurance	
구재영	with	Strike	
JaeYoung.Koo	Chanik.Jeon	Nam-sik.Min	
12/16	12/16	12/16	



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1. Revision History

Revision No	Originator	Description of changes	Date of changes
Ver 1.0	Chanik.Jeon	Issued	2009.12.16



2. Introduction

2.1 Introduction of Product

This product is an internal dielectric chip antenna that the Ag paste is printed on the surface of dielectric block.

2.2 Specification and Dimension

Туре	Only Bulk Ceramic				
Material	Dielectric Block		Mg₂SiO₄(Mag	nesium Silicat	e)
Material	Electrode Paste			Ag	
	$W = 2.0\pm0.1$				
Dimension [mm]	$L = 6.0\pm0.1$		Ag	Paste	
	T = 1.2±0.1	W			
Flatness	0.04	T	T		
MSL LEVEL	MSL Level 1	L	L Dielectric		
ESD LEVEL	More than 15 KV (HBM CLASS 3B)	Top-S	Top-Side View Bottom-Side View		m-Side View
Version	Revision 1.0				
Characteristic	Frequency VSWR(CTF)	Cycle of management	LOT	СРК	Page
inspection (CTF)	2400MHz 1.0 ~ 3.0 :	1 ALL	ALL	5.19	4,6,15 Page
(311)	2485MHz 1.0 ~ 3.0 :	1 ALL	ALL	5.17	4,6,15 Page

3. Special Management()

- The below things are special management items.

CTQ	The reason
Dimension & Weight (after forming)	The plasticity dielectric block is influenced at this item
Dimension (after Plasticity)	The accuracy of printed pattern is influenced at this item
Dimension of Printing Pattern	The accuracy of printed pattern is the most special thing at electrical characteristic of dielectric chip antenna

CTF 📀	The reason		
SWR Measurement	This item is an important parameter that fix an electrical characteristic		

- Care about the below things.

ITEM	Content		
Keeping	Sealing tightly when keeping for a long time		
Action	Maybe characteristics is changed when changed any design		



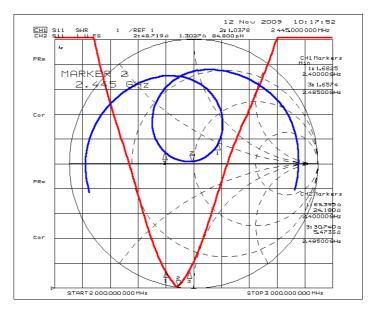
4. Electrical Characteristics

4.1 Set Condition

ITEM				SPEC
Frequency Range [MHz]				2400 ~ 2485
	SWR	[Max]		3.5 : 1 (Typ 3.0 : 1)
	Input Impe	edance $[\Omega]$		50 Ohm
	Polari	zation		Linear
	Total Gai	n (Peak / A	vg) [dBi]	0.6 / -3.4
			Peak	3.22
	Azimuth	Theta	Average	1.00
		Phi	Peak	-9.15
			Average	-14.97
	Elevation 1	Theta	Peak	-3.74
Gain [dBi]			Average	-10.27
		Phi	Peak	3.08
			Average	-1.96
	Elevation 2	Theta	Peak	-9.64
			Average	-16.99
		Phi	Peak	3.24
			Average	-1.62



4.2 S11 Graph of Set Condition

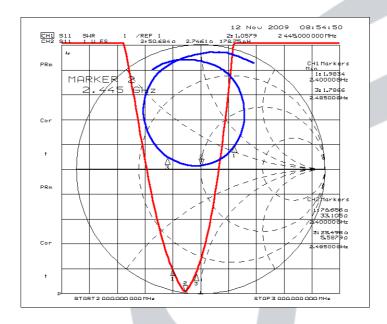


4.3 Test Fixture Condition

ITEM	SPEC
Frequency Range [MHz]	2400 ~ 2485
Lower Frequency (2400 MHz) SWR [Min~Max]	1.0 ~ 3.0 : 1 (Typ 2.5 : 1)
Upper Frequency (2485 MHz) SWR [Min~Max]	1.0 ~ 3.0 : 1 (Typ 2.5 : 1)

4.4 S11 Graph of Test Fixture Condition

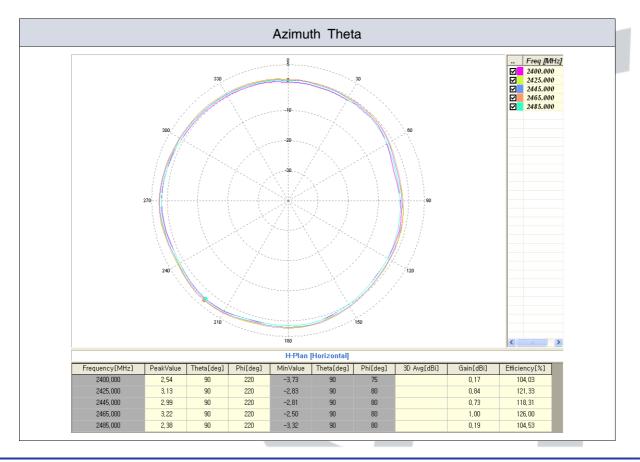




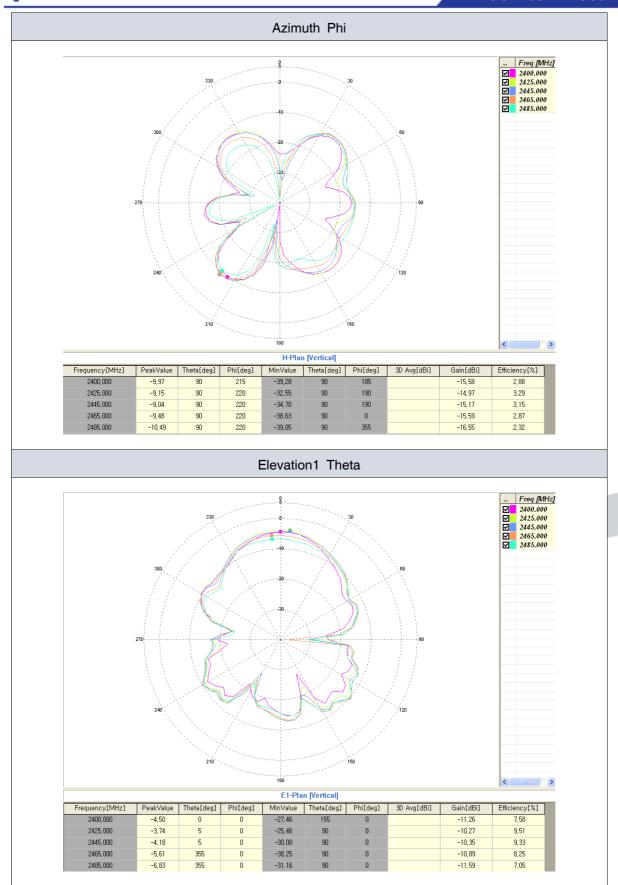


4.5 Radiation Pattern

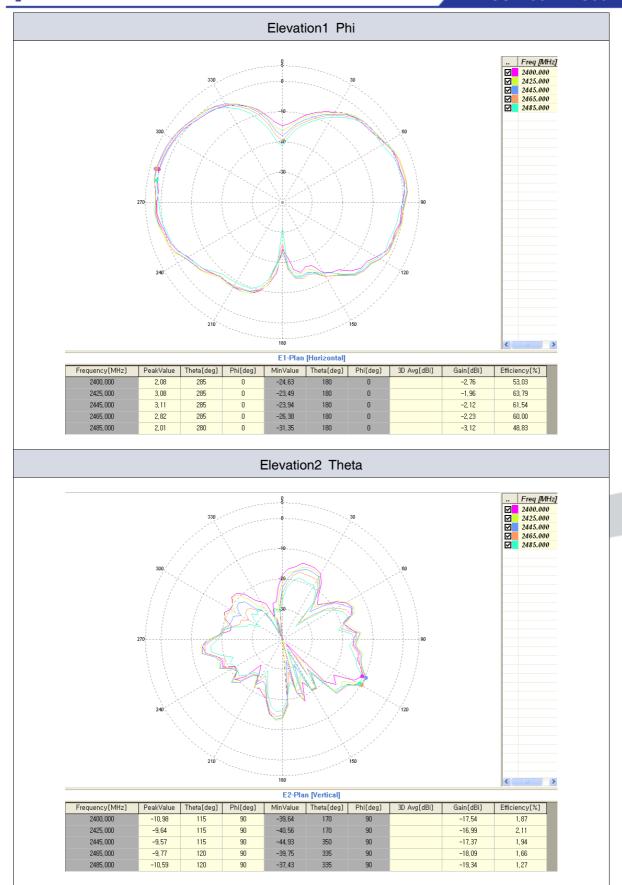
Azimuth Plane	Elevation1 Plane	Elevation2 Plane	
270° 90°	90° 270°	270° — 90° — 90° — 180°	
Theta	Vertical field of measured plane		
Phi	Horizontal field of measured plane		



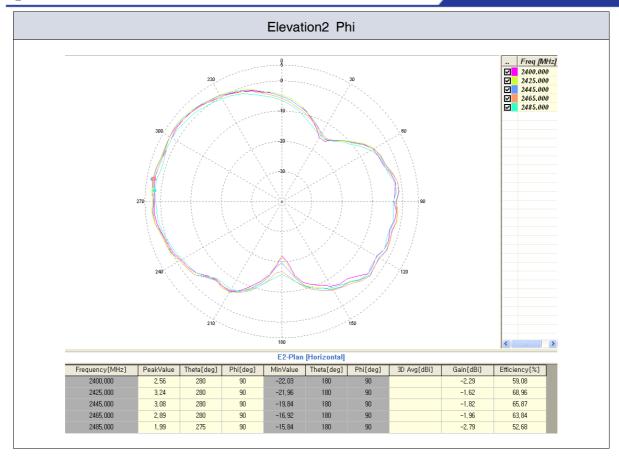












5. Measurement Process

5.1 SWR / Return loss

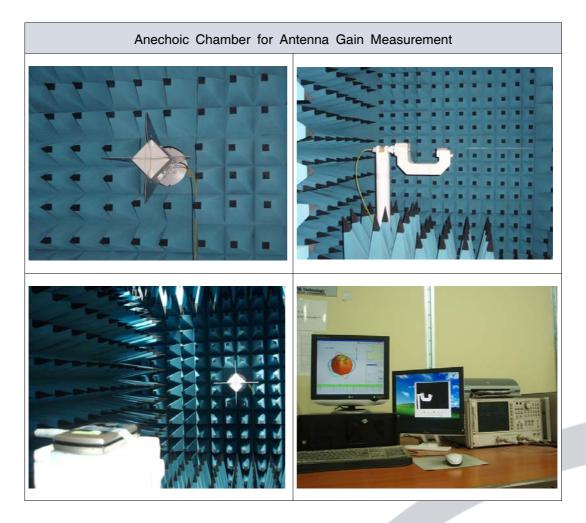
The SWR / Return loss is measured by Network Analyzer. Using the test fixture, the Selected reference sample is a standard product.

	Set Condition	Test Fixture Condition	
Network Analyzer	Agilent HP8753E	Agilent HP8753E or Advantest R3765CH	
Cable	RF cable(300mm)	RF cable(300mm)	
Test condition			

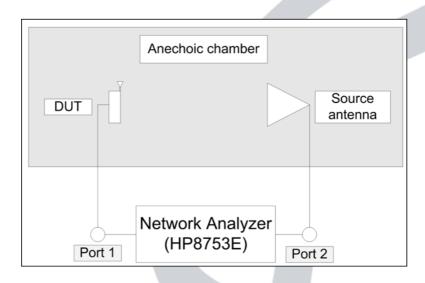


5.2 Gain

The Antenna Gain is measured by using the Passive DUT at Anechoic Chamber.



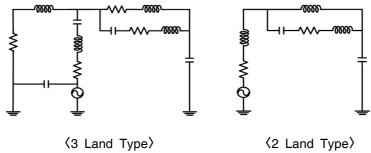
5.3 Gain Measurement block diagram





6. Internal Block Diagram

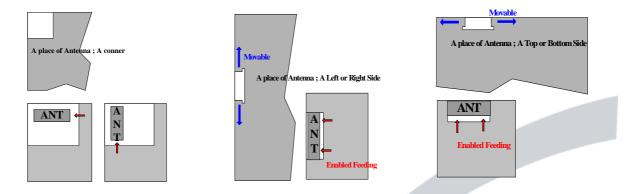
This product is made of the dielectric block and RF part materialized the characteristics by structural change of Ag pattern on the brick of dielectric block and conditioning value of the structural equivalent circuit.



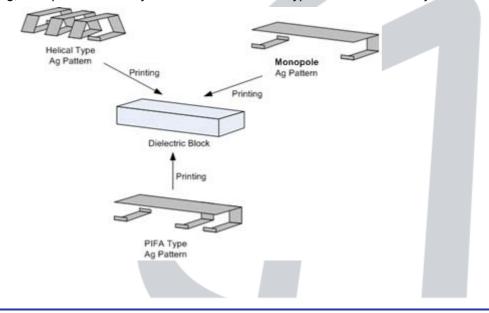
7. Basis Action / Application Note

This product is the internal dielectric chip antenna of radio communication, coverts the electric signal advanced along by transmission line into free space wave.

This product will be mounted wherever you want and the design is revised by mount condition. But required attention to select the mount position, because this product is the radiation part and changed characteristics by boundary condition.



As the following, this product is easy to revise the various types for the boundary condition.

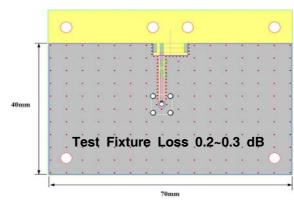




8. Measurement Jig SPEC

8.1 Test Fixture And GROUND Condition

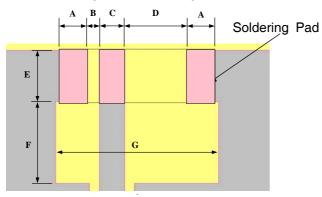


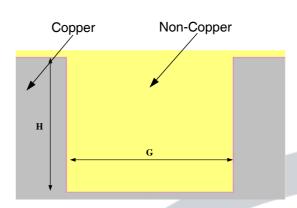


* Ev B'd and Test Fixture Jig is the same.

(Contact way of Ev B'd is soldering, Test Fixture is copper contact way.)

8.2 PCB Layout & Soldering Pad Dimension





Top Layout

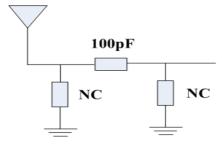
Bottom Pattern

Parameter	Α	В	С	D	Е	F	G	Н
Value[mm]	1.1	0.5	1.0	2.5	2.2	1.5	6.2	3.7

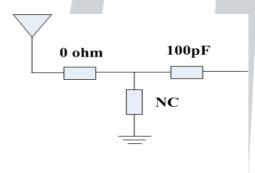
Unit; mm

Unless specified tolerances are ±0.05

8.3 Matching Circuit And Reference Value



π Matching

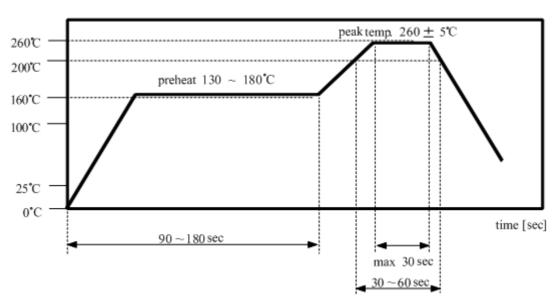


T Matching



9. Soldering Condition

9.1 Reflow Soldering



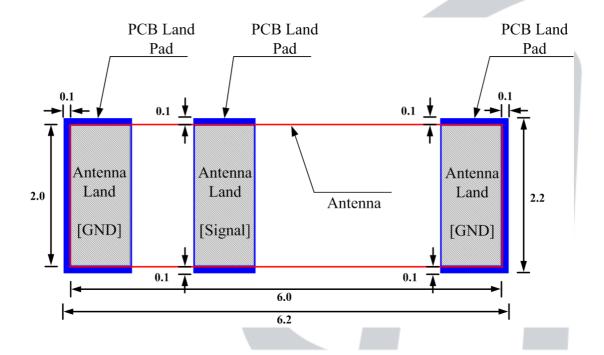
9.2 Manual Soldering

Pre-heating Temperature : 120 $^{\circ}$ C, 60 $^{\sim}$ 300 sec.

Soldering Temperature : 340 ± 5 $^{\circ}\mathrm{C}$, 5 sec max per each terminal

9.3 PCB Pattern Design

As the following, the PCB land pattern is laid out 0.1 mm outside land pattern of antenna more than indicated antenna land dimension.





10. Primary Inspection List

Item	Frequency [MHz]			Size [mm]		
Chandard	SWR 3	3.0 Max	W 00.01	1.00.04	T=1.2±0.1	
Standard	2400MHz	2485MHz	W=2.0±0.1	L=6.0±0.1	1=1.2±0.1	
1	1.98	1.78	2.02	6.01	1.23	
2	1.79	1.96	2.03	6.02	1.23	
3	1.93	1.83	2.03	6.03	1.23	
4	1.84	1.89	2.03	6.01	1.22	
5	1.91	1.82	2.02	6.01	1.23	
6	1.77	2.04	2.04	6.01	1.24	
7	1.84	1.93	2.02	6.02	1.24	
8	1.87	1.89	2.03	6.02	1.22	
9	1.82	1.97	2.02	6.02	1.24	
10	1.91	1.86	2.03	6.02	1.24	
11	1.99	1.79	2.03	6.03	1.23	
12	1.81	1.97	2.02	6.03	1.24	
13	1.82	1.98	2.04	6.02	1.22	
14	1.89	1.92	2.02	6.01	1.23	
15	1.91	1.89	2.03	6.01	1.23	
16	1.83	1.94	2.03	6.02	1.24	
17	1.76	1.99	2.02	6.03	1.22	
18	1.92	1.89	2.04	6.03	1.24	
19	1.72	2.00	2.02	6.01	1.23	
20	1.90	1.87	2.02	6.02	1.24	
Min	1.72	1.78	2.02	6.01	1.22	
Max	1.99	2.04	2.04	6.03	1.24	
X	1.86	1.91	2.02	6.01	1.23	
σ	0.07	0.07	0.01	0.01	0.01	
Cpk	5.17	4.97	3.28	3.38	2.91	
Result	ОК	ОК	ОК	ОК	ОК	



11. Reliability Condition

11.1 Environment Test

ITEM	TEST CONDITION	LIMIT
High Temperature Action	85℃±3℃, 1hr	
High Temperature Resistance	+85℃±3℃, 120hr±2hr	After test, Must meet
Low Temperature Action	-40℃±3℃, 1hr	the characteristics spec of
Low Temperature Resistance	-40℃±3℃, 120hr±2hr	4.4 list
Humidity Action	+85±3℃, RH85%	

11.2 Thermal shock test , Reflow test

ITEM	TEST CONDITION	LIMIT
Thermal shock	condition: -40°C±3°C/1min ↔ +85°C±3°C/1min Test Cycle: 32 cycle Temperature change time: within 5 min	After test, Must meet the characteristics spec of
Reflow	Pre Heating : 200±5℃, 30~60 sec Peak Heating : 260℃±5℃, 30sec Max	4.4 list

11.3 Mechanical Test

ITEM	TEST CONDITION	LIMIT
Vibration	Freq: 10~500Hz, Acceleration: 10 ×9.8 m/s (G) Sweep time: 15 min, X.Y.Z each 5 times	
Drop	18 times free fall Using the drop jig 152cm high Jig: 120g±20g Plastic Jig Bottom: Concrete or Iron	After test, Must meet the characteristics spec of 4.4 list

11.4 MSL LEVEL Test

1) JEDEC J-STD-020C Test

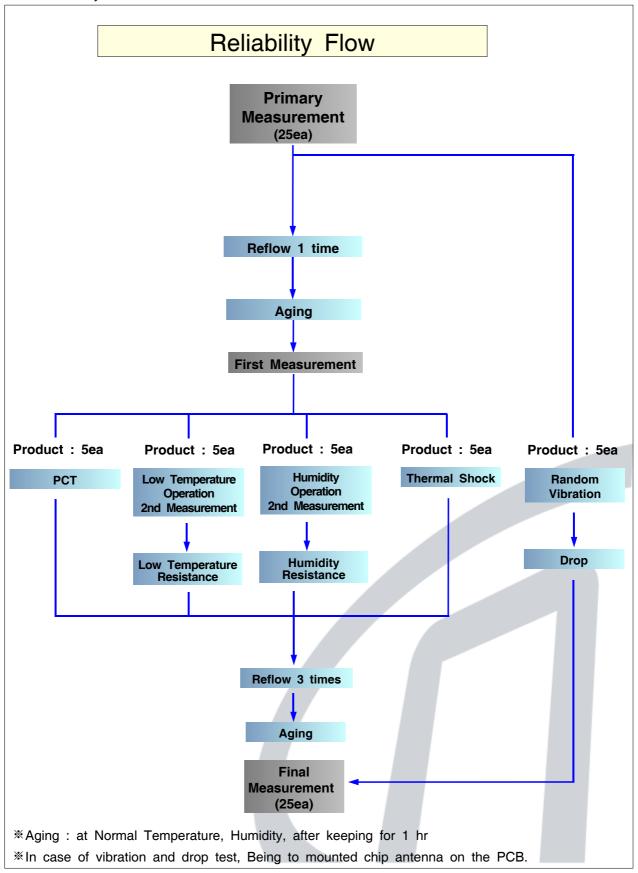
	Floor Life Time Conditions		Soak Requirements		
			Time	Conditions	
1	Unlimited	= < 30°C/85%RH	168+5/-0	= < 85℃/85%RH	

2) Test Condition

ITEM	Conditon		LIMIT
Soak Requirements	After leaving +85±3℃, RH85% 2 times Reflow without aging	168hr±2hr	After test, Must meet the characteristics spec of 4.4 list



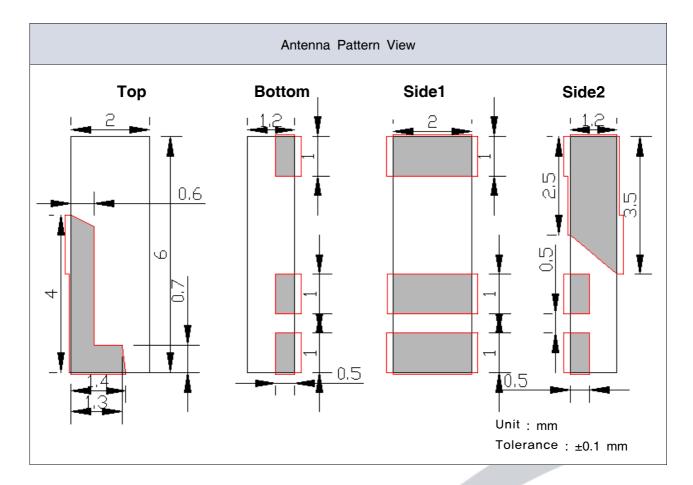
11.5 Reliability Flow



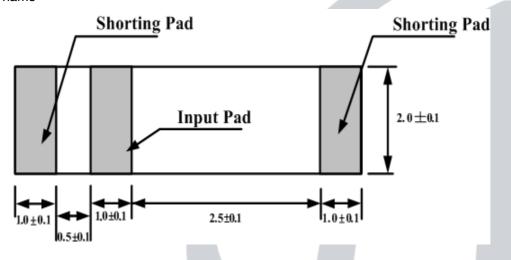


12. Mechanical Characteristics

12.1 Antenna Pattern Drawing



12.2 Pin name



* PCB Layout & Soldering Pad Dimension 은 13 page 8.2 도면 참조



12.3 Lot Notation

9 1 1

1 2 3

- ① Year : 1 2001, 2 2002, ···· 9 2009 ····
- 2 Month: 1 January, 2 February · · · · 9 September, A October, B November · · · ·
- ③ Date : 1 1st, 2 2nd · · · · 9 9th, A- 10th, B 11th · · · ·

12.4 Marking Specification





◀ <u>S30</u> <u>9</u> <u>1</u> <u>1</u>

1 2 3 4 5

- 1 Input Signal
- ② Serial
- ③ Year: 1-2001, 2-2002, ···· 9-2009 ····
- 4 Month: 1 January, 2 February · · · · 9 September, A October, B November · · · ·
- 5 Date : 1 1st , 2 2nd · · · · 9 9th, A 10th, B 11th · · · ·

12.5 Marking Method

Ink marking - Black Ink

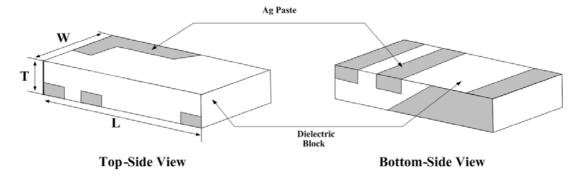


13. Structure & Material

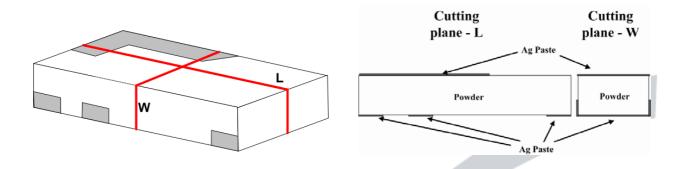
13.1 Fabrication

The structure is materialized by printing Ag paste at the dielectric block.

13.2 Structure



13.3 The cross section



13.4 Material

ITEM	Material	Maker	Printing pattern SPEC
Dielectric Block	Powder	SAM B00 CERAMIC	
PATTERN	Ag Paste	METECH	Thickness: TYP 10 //m
PAD	Ag paste	METECH	Thickness: Min 10 \(^{m}\) (TYP 16 ~ 20 \(^{m}\))



14. Attention

14.1 Temperature Condition

	Range	Unit
Operating Temperature	-40 ∼ +100℃	°C
Keeping Temperature	-40 ~ +70°C	°C

14.2 Temperature Test Condition

Item	Condition	Temperature Range
Operating Temperature	Low	at -75 ℃, for 24 hr, Good Operating
Operating Temperature	High	at +150 ℃, for 24 hr, Good Operating
Kaaning Tampagatura	Low	at -75 ℃, after 1000 hr, Good Operating
Keeping Temperature	High	at +85 °C, after 1000 hr, Good Operating

^{*} In case of "High Temperature Resistance", because the packing material is broken at higher temperature than +85 $\,^{\circ}$ C, the test is not able.

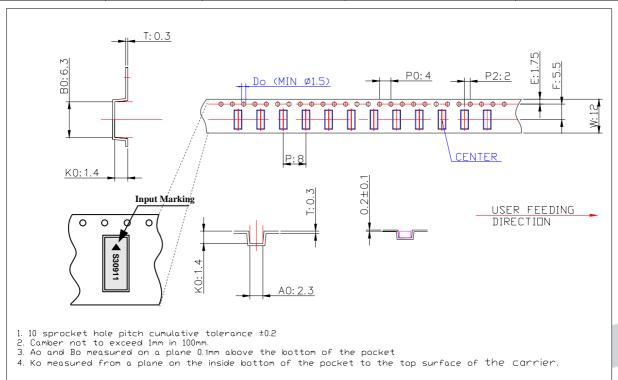




15. Packing

15.1 Carrier/Reel

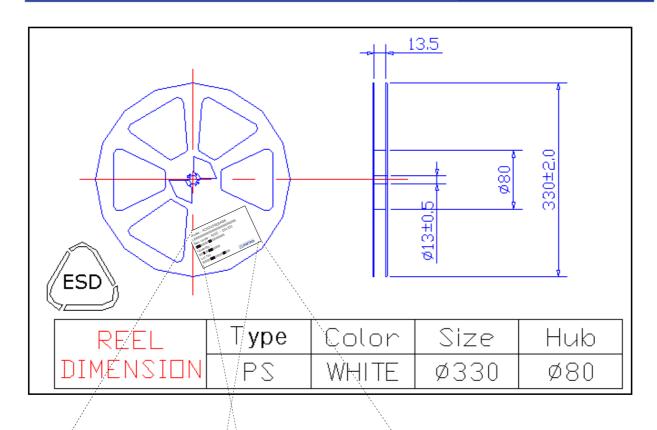
ITEM	Material	Surface Resistance	Electricity	method
Carrier	A-PET	Typical 10 ⁸ Ω	10V MAX	Lloot myooo
Cover tape	PET	Typical 10 ⁸ Ω	30V MAX	Heat press
Reel	PS	Typical 10 ⁸ Ω	30V MAX	-



DKC DWG. No	D-1208-052				
DIMENSIONAL UNIT					
UNTOLERANCE DIMENSION	ΞD	±0.1			
CAD FILE NA	ME	050504			
DESIGNED BY	K. M. J				
SCALE	1/1				
TITLE	יטטורנ				
	*6*1.2	R TAPE P(신)			
PART.	CARRIER TAPE				
MATERIAL	C-PET				
LENGTH	50.6M				
COUNT	6320P				

NAME	SPEC.
W	12,0±0,2
E	1.75±0.1
F	5.5±0.1
Do	1.5+0.1
Р	8.0±0.1
Ро	4.0±0.1
P2	2.0±0.1
Ao	2.3±0.1
Во	6.3±0.1
Ко	1.4±0.1
Т	0.3±0.05





CODE NO:

ACS2450FBAS30 Model:

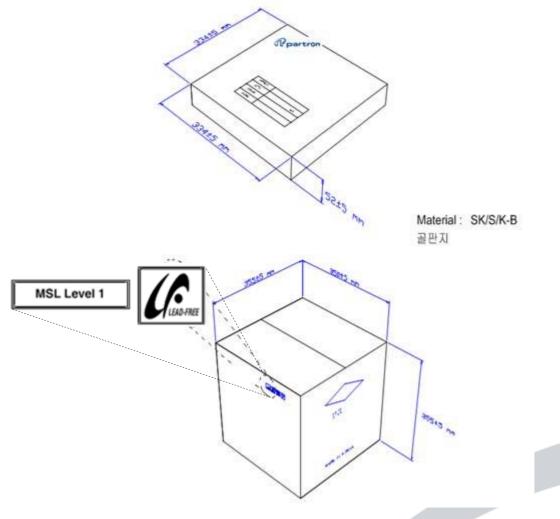
(I) PARTRON

MSL Level 1





15.2 BOX



15.3 Real Picture







Outer Box





Reel / Inner Box label

Outer Box label



16. Process Control

Product	Issue	ed/Revision		Record	By designed	By checked	By approved
CLUD ANTENNA	Issued	04.04.06	Process Control	DBCD C004			
CHIP ANTENNA	Revised	05.04.03		PRCP-C001			

			Ttovioca	00.01.0	. •											
Input	FLOW	CHART	Process		Manage	ement of Facto	rs		Management of quality							
Materials	prepar ation	Main Process	name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action		
Ceramic POWDER		\Diamond	Import Inspection						shrinking rate permittivity	refer to Guide Sheet	Micrometer Network	10ea/L0T	C/sheet	Return		
POWDER lubricant			powder	Mixer					mixing	POWDER lubricant	Scale	PER MIXING	-	Exhaust		
			Shaping CTQ	Press	pressure Mold Condition	refer to Guide Sheet	Per LOT 1/day	parameter C/SHEET	dimension weight density aspect	refer to Guide Sheet	Micrometer scale Calculated Visual	5/100EA 10ea/lot	LOT CARD	Exhaust		
			Plasticity	Plasticity Hole	SETTER Outside Temperature PROFILE	refer to Guide Sheet	all 2/day 1/month	C/sheet								
		\Diamond	Block CTQ						wide length shape	refer to Guide Sheet	Micrometer Calipers Visual Inspection	20ea/L0T 20ea/L0T all	C/sheet	Exhaust		
AG PASTE			SIDE1 PAD Printing CTQ	Printer screen	Squeeze velocity/presure SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework		
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework		

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	Produc	t	Is	sued/Revisio	n						Record	By designed	By chec	ked By	approved
СНІ	IP ANTI	ENNA	Issued Revise			Process Control					PRCP-C0	01			
Innut	FLOW	CHART	Process		Ma	anagem	ent of Factor	S			N	Management of qua	lity		
Input Materials	prepar ation	Main Process	name	Equipment Name	Check	ked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
AG PASTE			SIDE 2 PAD Printing CTQ	Printer screen	Squee: velocity/p SNAI	oresure	refer to Guide Sheet	1/day	_	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Tempera Belt sp		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Tempera Belt s		refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework
AG PASTE			TOP printing CTQ	Printer screen	Squee: velocity/p SNAI	eze oresure P	refer to Guide Sheet	1/day	_	PATTERN dimension	refer to Guide Sheet	measure	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Tempera Belt sp		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
AG PASTE			BOTTOM PAD Printing CTQ	printer screen	Squee: velocity/p SNAI	eze presure P	refer to Guide Sheet	1/day	-	PATTERN dimension aspect	refer to Guide Sheet	measure Microscope	10ea/3Jig	c/sheet	Rework

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Product	Issue	ed/Revision		Record	By designed	By checked	By approved
CHIP ANTENNA	Issued Revised	04.04.06 05.04.03	Process Control	PRCP-C001			

Input Materials	FLOW	CHART	Process		Manager	ment of Facto	rs				Management of qua	ality		
	prepar ation	Main Process	name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework
		\Diamond	aspect inspection						aspect	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot card production diary	Exhaust repair
			MARKING	Marking Machine					marking	Reference SPL	Visual Inspection	all	Lot card production diary	Rework Exhaust
		\Diamond	Electrical Characteristic CTF	NETWORK Inspection Jig	proofreading Condition	refer to Guide Sheet	1/2hour	C/sheet	VSWR 2400MHz:3.0:1 2485MHz:3.0:1 CTF	refer to Guide Sheet	Network	all	Lot card production diary	Exhaust repair
		\Diamond	aspect inspection						aspect dimension	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot card production diary	Exhaust repair
Carrier cover reel			Taping						Quantity Direction aspect	refer to Guide Sheet	Manua I	all	Lot card production diary	Rework
		\Diamond	shipper inspection	NETWORK Inspection Jig	proofreading Condition	refer to Guide Sheet	1/person	C/sheet	Electrical Characteristic aspect packing	refer to Guide Sheet	Network microscope Visual Inspection	refer to Guide Sheet	Result Paper	return Exhaust
packing box label			packing	bar code printer					packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	_	Rework
			packing inspection						packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	_	return

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17. RoHS Data

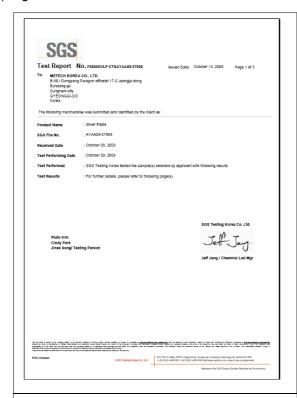
1) Ceramic Powder



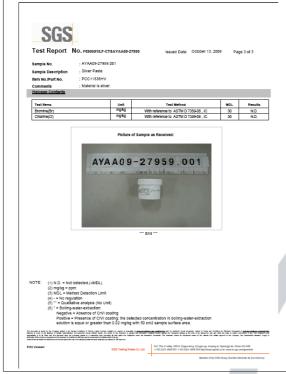




2) Ag Paste









3) Marking Ink



